

## HIGH SIDE SMART POWER SOLID STATE RELAY

TYPE	V <sub>DSS</sub>	R <sub>DS(on</sub> )	lout	Vcc
VN02AN	60 V	0.35 Ω	7 A	36 V

- OUTPUT CURRENT (CONTINUOUS): 7A @ T<sub>c</sub>=25°C
- LOGIC LEVEL 5V COMPATIBLE INPUT
- THERMAL SHUT-DOWN
- UNDER VOLTAGE PROTECTION
- OPEN DRAIN DIAGNOSTIC OUTPUT
- FAST DEMAGNETIZATION OF INDUCTIVE LOAD

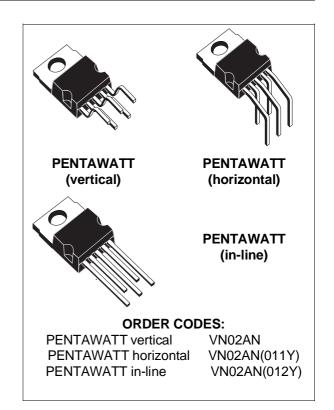
#### **DESCRIPTION**

The VN02AN is a monolithic device made using STMicroelectronics VIPower Technology, intended for driving resistive or inductive loads with one side grounded.

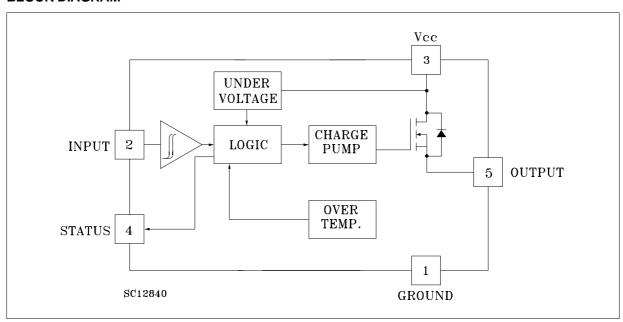
Built-in thermal shut-down protects the chip from over temperature and short circuit.

The diagnostic output indicates an over temperature status.

Fast turn-off of inductive load is achieved by negative (-18 V) load voltage at turn-off.



#### **BLOCK DIAGRAM**

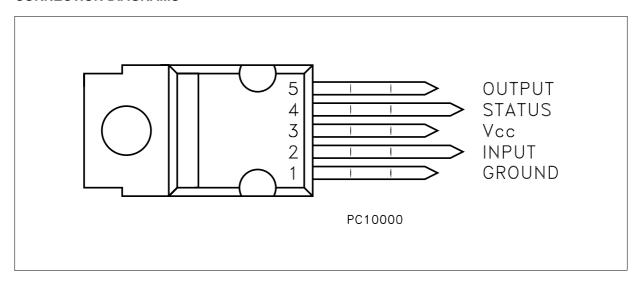


July 1998 1/11

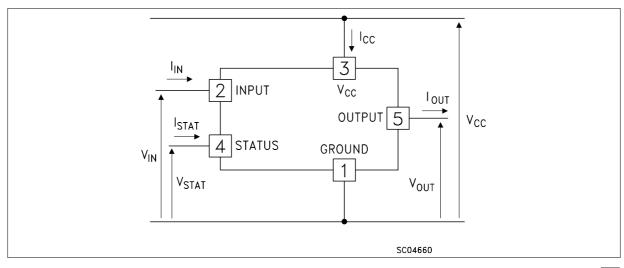
#### **ABSOLUTE MAXIMUM RATING**

Symbol	Parameter	Value	Unit
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	60	V
I <sub>OUT</sub>	Output Current (cont.)	7	А
I <sub>R</sub>	Reverse Output Current	-7	А
I <sub>IN</sub>	Input Current	±10	mA
-Vcc	Reverse Supply Voltage	-4	V
I <sub>STAT</sub>	Status Current (sink)	±10	mA
V <sub>ESD</sub>	Electrostatic Discharge (1.5 kΩ, 100 pF)	2000	V
Ptot	Power Dissipation at T <sub>c</sub> ≤ 25 °C	31	W
Tj	Junction Operating Temperature	-40 to 150	°C
T <sub>stg</sub>	Storage Temperature	-55 to 150	°C

#### **CONNECTION DIAGRAMS**



### **CURRENT AND VOLTAGE CONVENTIONS**



#### **THERMAL DATA**

R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	4	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambier	nt Max	60	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $V_{CC} = 9$ to 36 V; $T_{case} = 25$ $^{o}C$ unless otherwise specified) POWER

Symbo	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>CC</sub> *	Supply Voltage	-40 °C < T <sub>j</sub> < 125 °C	7		36	V
Ron	On State Resistance	$I_{OUT} = 3 \text{ A}$ $I_{OUT} = 1 \text{ A}$ $V_{CC} = 30 \text{ V}$ $T_j = 125  ^{\circ}\text{C}$			0.35 0.6	$\Omega$
Is	Supply Current	Off State $V_{CC} = 30 \text{ V}$ On State $V_{CC} = 30 \text{ V}$ On State $V_{CC} = 30 \text{ V}$ $T_j = 125 ^{\circ}\text{C}$			1 9 7	mA mA mA

### **SWITCHING**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time Of Output Current	I <sub>OUT</sub> = 3 A Resistive Load Input Rise Time < 0.1 μs		15		μs
tr	Rise Time Of Output Current	I <sub>OUT</sub> = 3 A Resistive Load Input Rise Time < 0.1 μs		15		μs
$t_{d(off)}$	Turn-off Delay Time Of Output Current	I <sub>OUT</sub> = 3 A Resistive Load Input Rise Time < 0.1 μs		14		μs
t <sub>f</sub>	Fall Time Of Output Current	I <sub>OUT</sub> = 3 A Resistive Load Input Rise Time < 0.1 μs		4.5		μs
(di/dt) <sub>on</sub>	Turn-on Current Slope	I <sub>OUT</sub> = 3 A 25 °C < T <sub>j</sub> < 125 °C I <sub>OUT</sub> = I <sub>OV</sub> 25 °C < T <sub>j</sub> < 125 °C			0.5 1	A/μs A/μs
(di/dt) <sub>off</sub>	Turn-off Current Slope	I <sub>OUT</sub> = 3 A 25 °C < T <sub>j</sub> < 125 °C I <sub>OUT</sub> = I <sub>OV</sub> 25 °C < T <sub>j</sub> < 125 °C			1.5 4	A/μs A/μs
V <sub>DEMAG</sub>	Inductive Load Clamp Voltage	$I_{OUT} = 3 A$ $-40  ^{\circ}\text{C} < T_{j} < 125  ^{\circ}\text{C}$	-24	-18	-14	V

# LOGIC INPUT (-40 $^{o}C \leq T_{j} \leq$ 125 $^{o}C$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
VIL	Input Low Level Voltage				8.0	V
V <sub>IH</sub>	Input High Level Voltage		2		(*)	V
$V_{I(hyst.)}$	Input Hysteresis Voltage			0.5		V
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = 5 V V <sub>IN</sub> = 2 V V <sub>IN</sub> = 0.8 V	25	250	600 300	μΑ μΑ μΑ
VicL	Input Clamp Voltage	I <sub>IN</sub> = 10 mA I <sub>IN</sub> = -10 mA	5.5	6 -0.7	-0.3	V V

## **ELECTRICAL CHARACTERISTICS** (continued)

PROTECTION AND DIAGNOSTICS (-40  $^{\circ}C \le T_j \le 125$   $^{\circ}C$  unless otherwise specified)

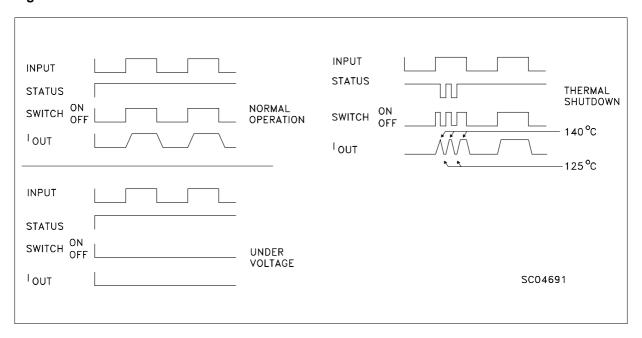
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>STAT</sub>	Status Voltage Output Low	I <sub>STAT</sub> = 1.6 mA			0.4	V
I <sub>STAT</sub>	Status Leakage Current	V <sub>STAT</sub> = 5 V			10	μΑ
Vusd	Under Voltage Shut Down		3.5	6	7	V
V <sub>SCL</sub>	Status Clamp Voltage	I <sub>STAT</sub> = 10 mA I <sub>STAT</sub> = -10 mA	5.5	6 -0.7	-0.3	V
lov	Over Current	$R_{LOAD} < 10 \text{ m}\Omega$		15		Α
l <sub>av</sub>	Average Current In Short Circuit	$R_{LOAD} < 10 \text{ m}\Omega$ $T_c = 85  ^{\circ}\text{C}$		0.6		А
$I_{DOFF}$	Leakage Current	V <sub>CC</sub> = 30 V			1	mA
T <sub>TSD</sub>	Thermal Shut-down Temperature		140			°C
T <sub>R</sub>	Reset Temperature		125			°C

<sup>(\*)</sup> The Vih is internally clamped at about 6V. It is possible to connect this pin to a higher voltage via an external resistor calculated to not exceed 10 mA at the input pin.

#### **TRUTH TABLE**

	INPUT	DIAGNOSTIC	OUTPUT
Normal Operation	L H	H H	L H
Over-temperature	Н	L	L
Under-voltage	X	Н	L

Figure 1: Waveforms



#### **FUNCTIONAL DESCRIPTION**

The device has a diagnostic output which indicates over temperature conditions.

The truth table shows input, diagnostic output status and output voltage level in normal operation and fault conditions. The output signals are processed by internal logic.

To protect the device against short circuit and over current conditions, the thermal protection turns the integrated Power MOS off at a minimum junction temperature of 140  $^{\rm o}$ C. When the temperature returns to 125  $^{\rm o}$ C the switch is automatically turned on again. To ensure the protection in all V<sub>CC</sub> conditions and in all the junction temperature range it is necessary to limit the voltage drop across Drain and Source (pin 3 and 5) at 28V according to:

 $V_{ds} = V_{CC} - I_{OV} * (R_i + R_w + R_l)$  where:

R<sub>i</sub> = internal resistence of Power Supply

R<sub>w</sub> = Wires resistance

R<sub>I</sub> = Short Circuit resistance

Driving inductive loads, an internal function of the device ensures the fast demagnetization with typical voltage ( $V_{demag}$ ) of -18V.

This function allows the reduction of the power dissipation according to the formula:

 $P_{dem} = 0.5 * L_{load} * (I_{load})^2 * [(V_{CC} + V_{dem})/V_{dem}] * f$ 

where f = Switching Frequency

Based on this formula it is possible to know the value of inductance and/or current to avoid a thermal shut-down.

# PROTECTING THE DEVICE AGAINST REVERSE BATTERY

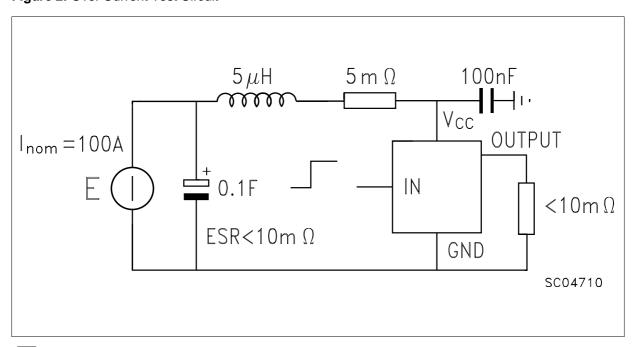
The simpliest way to protect the device against a continuous reverse battery voltage (-36V) is to insert a Schottky diode between pin 1 (GND) and ground, as shown in the typical application circuit (Fig. 3). The consequences of the voltage drop across this diode are as follows:

If the input is pulled to power GND, a negative voltage of  $\text{-V}_f$  is seen by the device. (V<sub>iI</sub>, V<sub>ih</sub> thresholds and Vstat are increased by V<sub>f</sub> with respect to power GND).

The undervoltage shut-down level is increased by  $V_{\rm f.}$ 

If there is no need for the control unit to handle external analog signals referred to the power GND, the best approach is to connect the reference potential of the control unit to node [1] (see application circuit in fig. 4), which becomes the common signal GND for the whole control board avoiding shift of V<sub>ih</sub>, V<sub>il</sub> and V<sub>stat</sub>. This solution allows the use of a standard diode.

Figure 2: Over Current Test Circuit



477

Figure 3: Typical Application Circuit With A Schottky Diode For Reverse Supply Protection

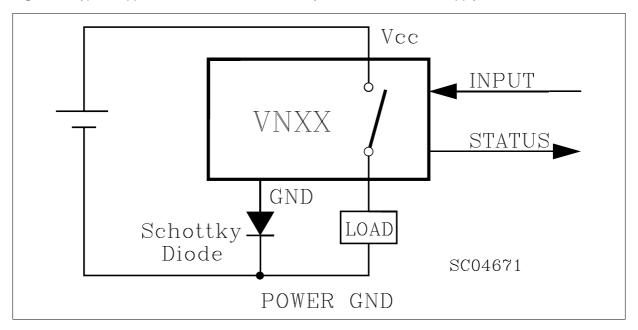
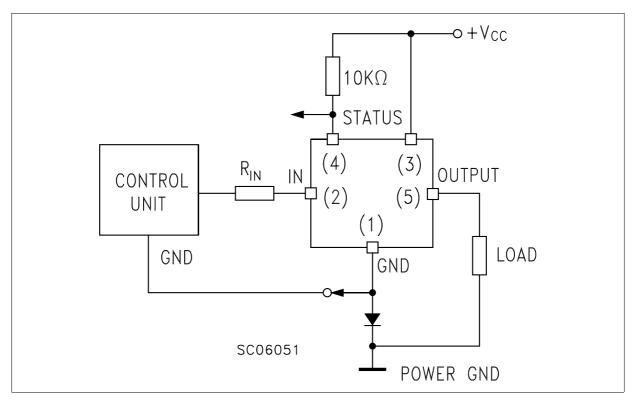
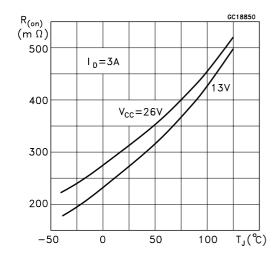


Figure 4: Typical Application Circuit With Separate Signal Ground

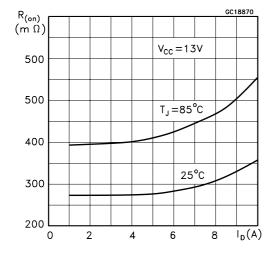


6/11 **L**77

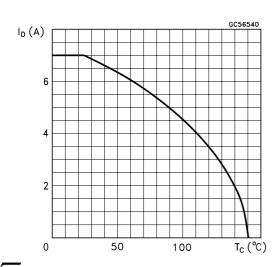
## R<sub>DS(on)</sub> vs Junction Temperature



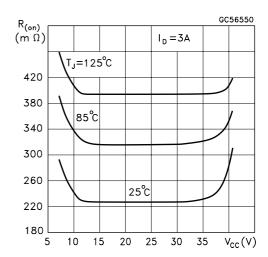
## R<sub>DS(on)</sub> vs Output Current



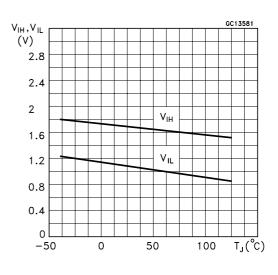
## **Output Current Derating**



## R<sub>DS(on)</sub> vs Supply Voltage

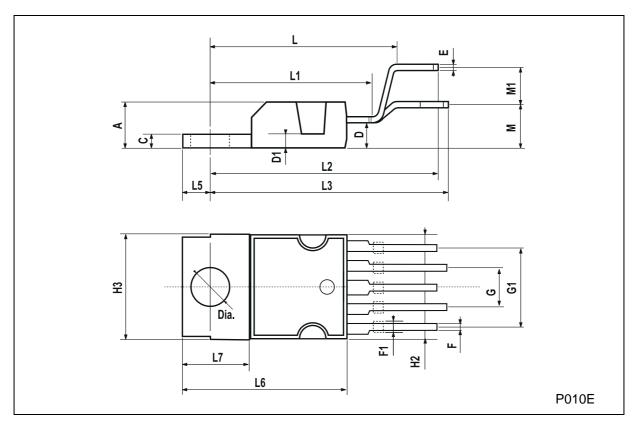


## Input Voltages vs Junction Temperature



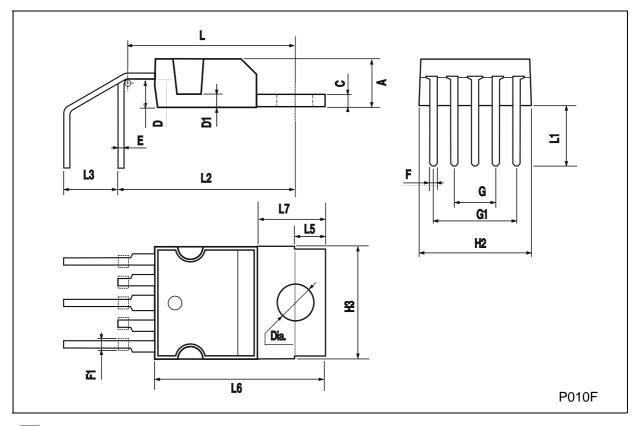
# PENTAWATT (VERTICAL) MECHANICAL DATA

DIM		mm			inch	
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
Е	0.35		0.55	0.014		0.022
F	0.8		1.05	0.031		0.041
F1	1		1.4	0.039		0.055
G	3.2	3.4	3.6	0.126	0.134	0.142
G1	6.6	6.8	7	0.260	0.268	0.276
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L		17.85			0.703	
L1		15.75			0.620	
L2		21.4			0.843	
L3		22.5			0.886	
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.260
М		4.5			0.177	
M1		4			0.157	
Dia	3.65		3.85	0.144		0.152



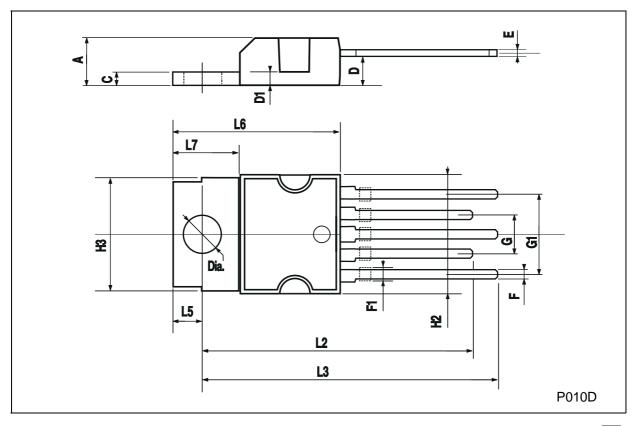
# PENTAWATT (HORIZONTAL) MECHANICAL DATA

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
E	0.35		0.55	0.014		0.022
F	0.8		1.05	0.031		0.041
F1	1		1.4	0.039		0.055
G	3.2	3.4	3.6	0.126	0.134	0.142
G1	6.6	6.8	7	0.260	0.268	0.276
H2			10.4			0.409
Н3	10.05		10.4	0.396		0.409
L	14.2		15	0.559		0.590
L1	5.7		6.2			0244
L2	14.6		15.2			0.598
L3	3.5		4.1	0.137		0.161
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.260
Dia	3.65		3.85	0.144		0.152



# PENTAWATT (IN-LINE) MECHANICAL DATA

DIM.		mm		inch		
DIIVI.	MIN	TYP	MAX	MIN	TYP	MAX
Α			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
Е	0.35		0.55	0.014		0.022
F	0.8		1.05	0.031		0.041
F1	1		1.4	0.039		0.055
G	3.2	3.4	3.6	0.126	0.134	0.142
G1	6.6	6.8	7	0.260	0.268	0.276
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L2	23.05	23.4	23.8	0.907	0.921	0.937
L3	25.3	25.65	26.1	0.996	1.010	1.028
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.260
Diam.	3.65		3.85	0.144		0.152



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